



DINGKIN

4406

30V N-Channel Enhancement Mode MOSFET

## Description

The JCW024DNC uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

## Application

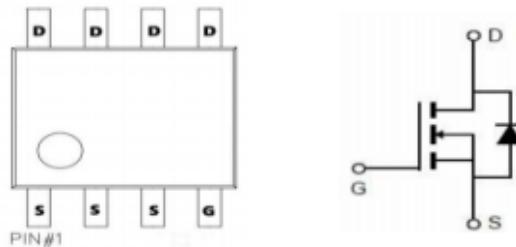
- Battery protection
- Load switch
- Uninterruptible power supply

## General Features

- $V_{DS} = 30V$   $I_D = 8A$
- $R_{DS(ON)} < 28m\Omega$  @  $V_{GS}=10V$
- $R_{DS(ON)} < 40m\Omega$  @  $V_{GS}=4.5V$



## SOP-8L Pin Configuration



## Package Marking and Ordering Information

Product ID	Package	Marking	QTY(PCS)	Packing method
JCW024DNC	SOP8	024DNC	3000	Reel

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS}$ @ 10V <sup>1</sup>	8	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS}$ @ 10V <sup>1</sup>	5.8	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	30	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	20	mJ
$I_{AS}$	Avalanche Current	22	A
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	4.5	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	50	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	30	°C/W



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## Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	30	33	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.027	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=5\text{A}$	---	19	28	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=3\text{A}$	---	24	40	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage		1.0	1.5	2.4	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	---	-5.8	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{\mu A}$
		$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	10	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=10\text{A}$	---	5.8	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	2.2	3.8	
$Q_g$	Total Gate Charge (4.5V)	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=10\text{A}$	---	12.6	17.6	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	4.2	5.9	
$Q_{\text{gd}}$	Gate-Drain Charge		---	5.1	7.1	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_g=3.3\text{ }\Omega$ $I_D=10\text{A}$	---	6.2	12.4	ns
$T_r$	Rise Time		---	59	106	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	27.6	55	
$T_f$	Fall Time		---	8.4	16.8	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	960	---	pF
$C_{\text{oss}}$	Output Capacitance		---	139	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	87	---	
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	10.3	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	42	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=10\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ $T_J=25^\circ\text{C}$	---	12.5	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	5	---	nC

Note :

1 . The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ 3 . The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $L=0.1\text{mH}$ , $I_{\text{AS}}=35\text{A}$ 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



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## Typical Characteristics

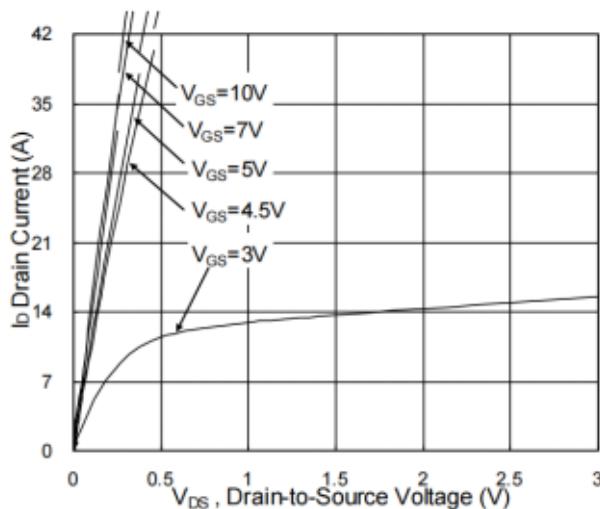


Fig.1 Typical Output Characteristics

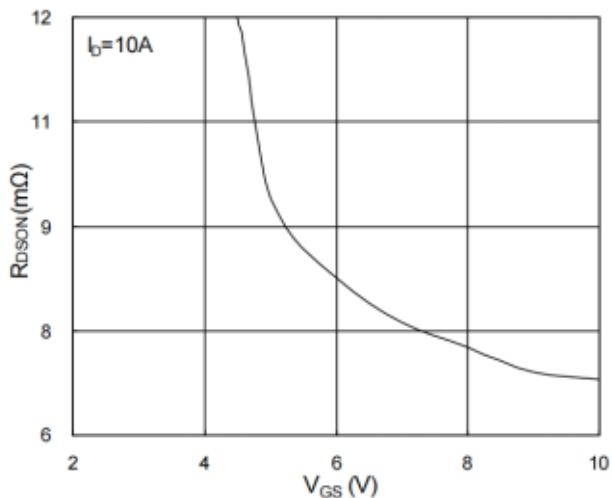


Fig.2 On-Resistance vs. Gate-Source

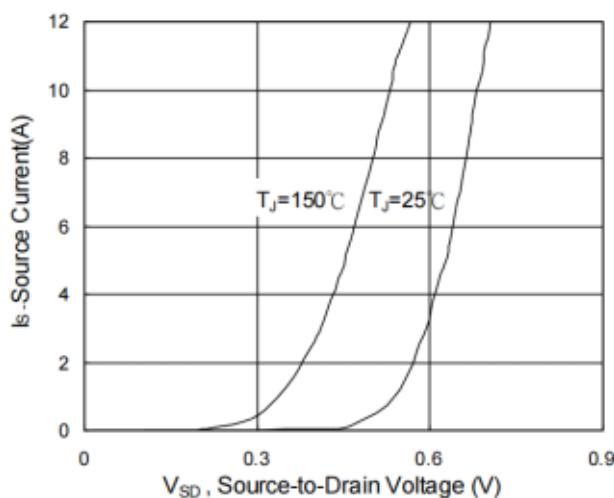


Fig.3 Forward Characteristics of reverse

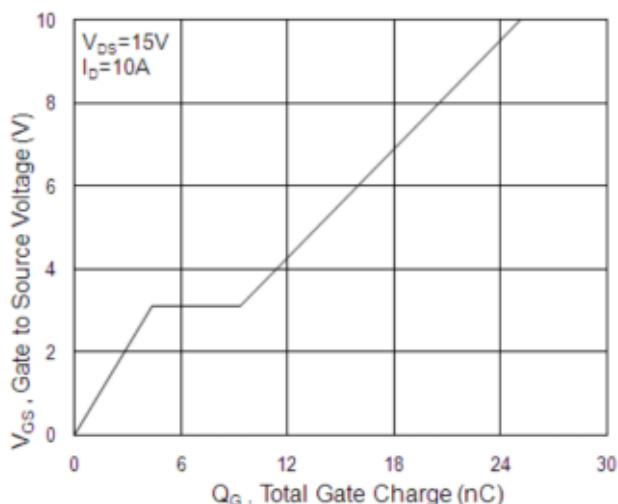


Fig.4 Gate-Charge Characteristics

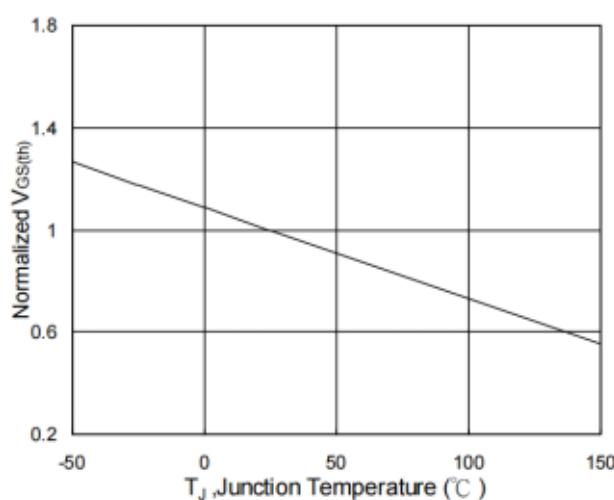


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

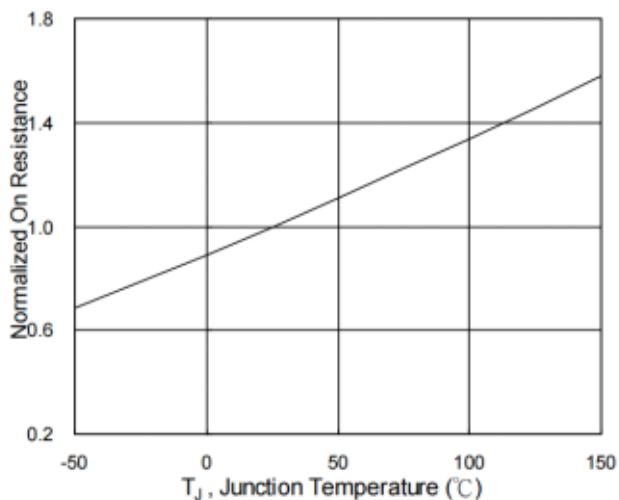


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$



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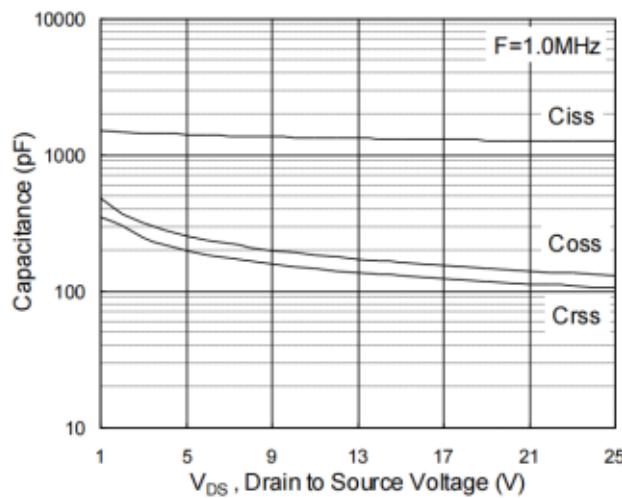


Fig.7 Capacitance

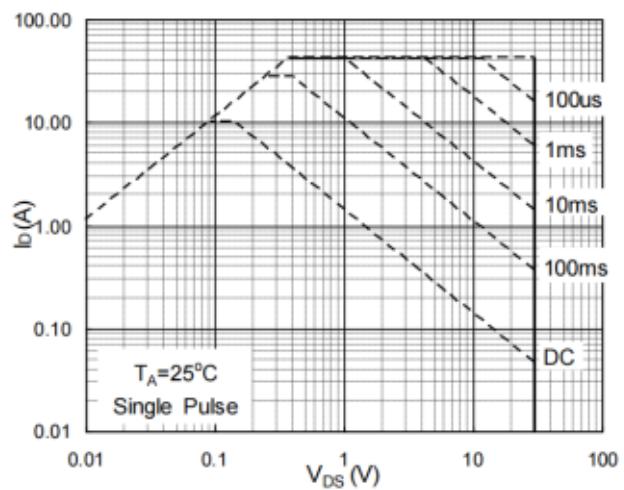


Fig.8 Safe Operating Area

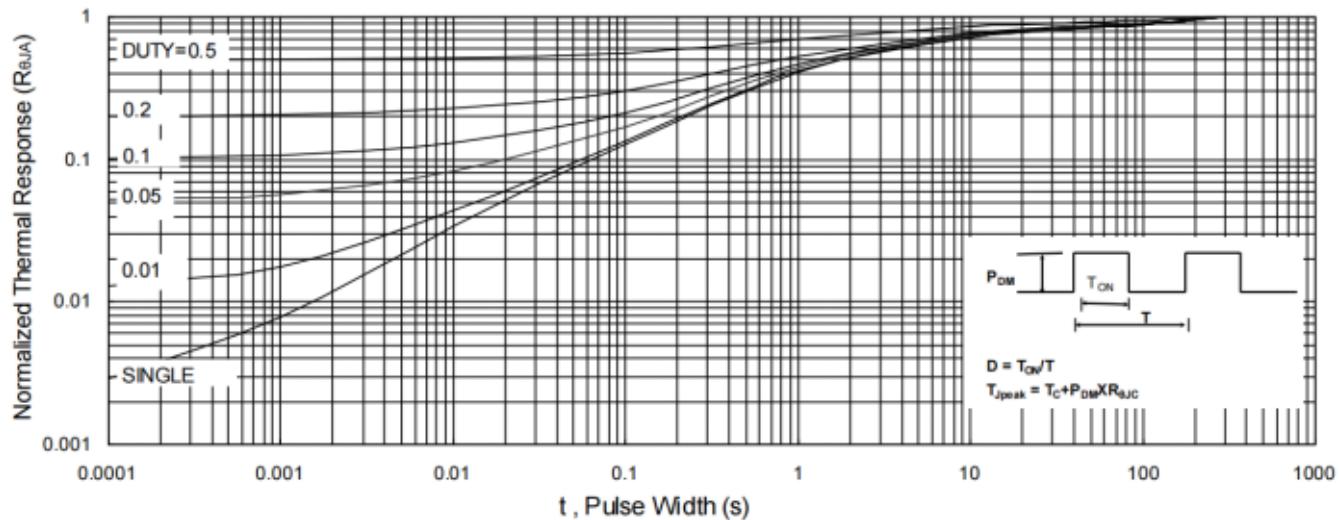


Fig.9 Normalized Maximum Transient Thermal Impedance

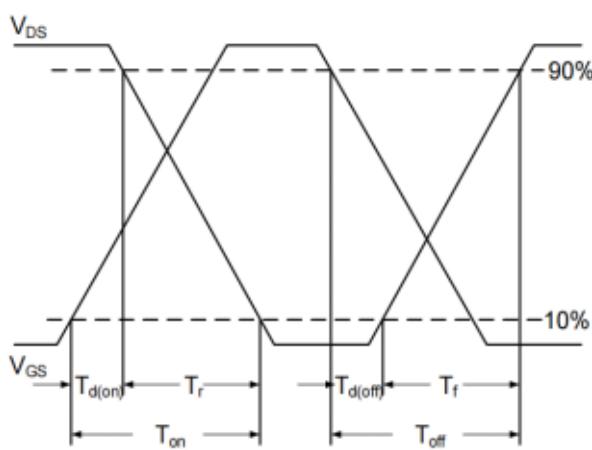


Fig.10 Switching Time Waveform

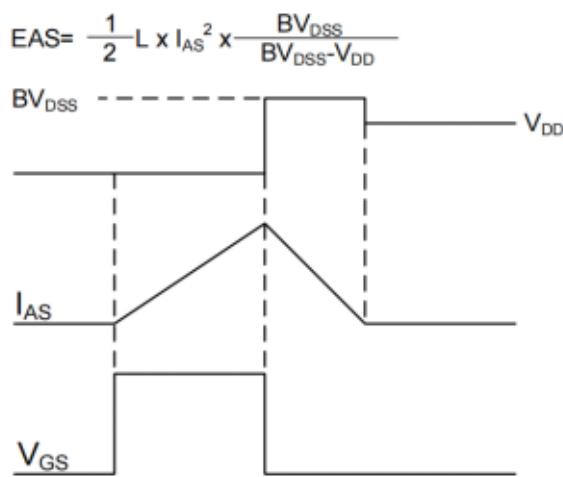


Fig.11 Unclamped Inductive Switching Waveform

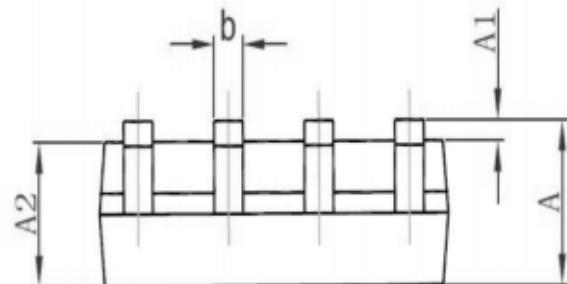
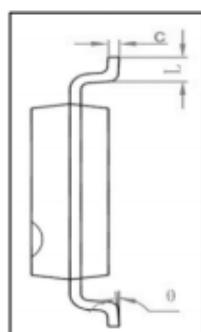
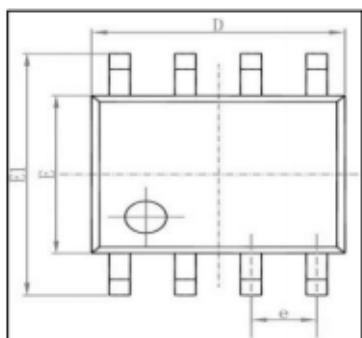


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## Package Mechanical Data-SOP-8/ESOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
$\theta$	0°	8°	0°	8°

